

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application:

**Listing of Claims**

Claims 1-5 (canceled)

6. (currently amended) A method for fabricating a semiconductor device, comprising the steps of:

forming a ~~semiconductor~~ layer including at least a gate insulation layer;

forming a silicon layer on the gate insulation layer;

forming a reaction prevention layer on the silicon layer, the reaction prevention layer containing nitrogen and silicon and having a surface density of nitrogen above about  $1 \times 10^{15}/\text{cm}^2$ ;

forming a metal layer on the reaction prevention layer;

forming a stack gate electrode by etching sequentially the metal layer, the reaction prevention layer and the silicon layer; and

performing a selective oxidation process oxidizing selectively the silicon layer from the stack gate electrode.

7. (currently amended) The method as recited in claim 6, wherein at the step of forming the reaction prevention layer, the ~~silicon~~ reaction prevention layer is formed by performing a decoupled plasma nitridation technique or a remote plasma nitridation technique in an atmosphere of a gas selected from a group consisting of  $\text{NH}_3$ ,  $\text{ND}$ , where D is deuterium,  $\text{N}_2$  and  $\text{NF}_3$  or a mixed gas of the above as simultaneously as by maintaining a substrate temperature in a range from about  $0^\circ\text{C}$  to about  $700^\circ\text{C}$  and ~~supplying~~ a RF power ~~of~~ is below about 1000 W.

8. (original) The method as recited in claim 6, wherein at the step of forming the reaction prevention layer, a surface of the silicon layer is proceeded with a thermal treatment performed at a temperature ranging from about  $750^\circ\text{C}$  to about  $950^\circ\text{C}$  for about 10 seconds to about 100 seconds in an atmosphere of  $\text{NH}_3$  or  $\text{ND}_3$ .

9. (original) The method as recited in claim 6, wherein the reaction prevention layer is a silicon nitride layer formed through the use of a chemical vapor deposition technique or an atomic layer deposition technique.

10. (original) The method as recited in claim 6, wherein the reaction prevention layer is formed with a thickness thicker than about 1.2 nm but thinner than about 3 nm.